

INTERCONNECTS

SERIES 850, 851, 852, 853 • 1,27 GRID HEADERS AND SOCKETS • SINGLE AND DOUBLE ROW STRIPS

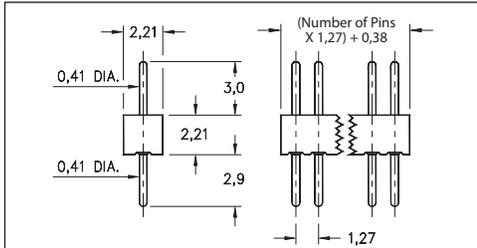


FIG. 1

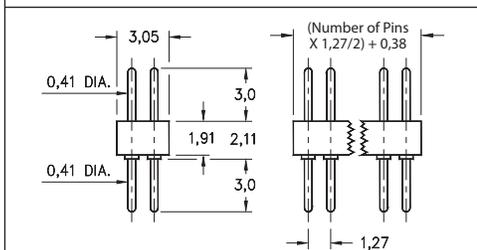


FIG. 2

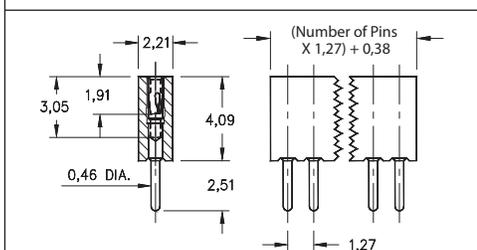


FIG. 3

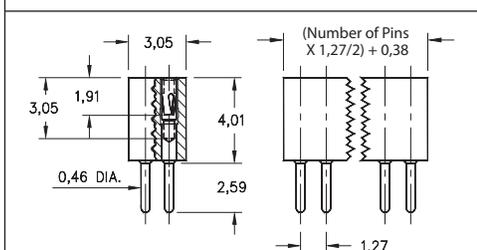


FIG. 4

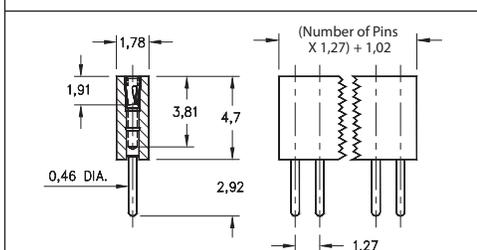
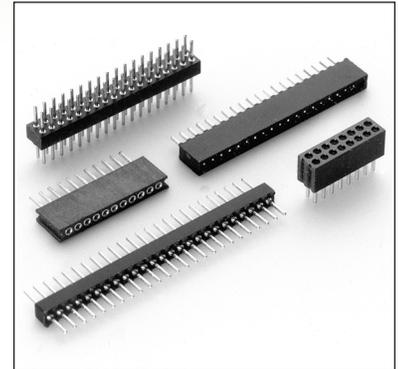


FIG. 5

- Series 850, 851, 852, 853 single and double row interconnects have 1,27 pin spacing and permit board stacking as low as 6,3
- Pin headers have 0,41 dia. pins (MM #4006-0) See page 208 for details
- MM #0467 and MM #4890 receptacles use Hi-Rel, 3-finger BeCu #11 contact rated at 3 amps. (#11 contact accepts pin diameters from 0,38 - 0,51). See pages 158 and 160 for details
- Insulators are high temperature thermoplastic, suitable for all soldering operations



ORDERING INFORMATION

FIG. 1	Series 850...001	Single Row 2,21 Profile Pin Header				
		850-XX-0__-10-001000 Specify number of pins 01-50				
FIG. 2	Series 852...001	Double Row 2,11 Profile Pin Header				
		852-XX-__-10-001000 Specify number of pins 002-100				
SPECIFY PLATING CODE XX=		10	90	40		
Pin Plating		0,25µm Au	5,08µm Sn/Pb	5,08µm Sn		
FIG. 3	Series 851...001	Single Row 4,09 Profile Socket				
		851-XX-0__-10-001000 Specify number of pins 01-50				
FIG. 4	Series 853...001	Double Row 4,09 Profile Socket				
		853-XX-__-10-001000 Specify number of pins 002-100				
FIG. 5	Series 851...002	Single Row 4,7 Profile Socket				
		851-XX-0__-10-002000 Specify number of pins 01-77				
SPECIFY PLATING CODE XX=		91	93	99	41	43
Sleeve (Pin)		5,08µm Sn/Pb	5,08µm Sn/Pb	5,08µm Sn/Pb	5,08µm Sn	5,08µm Sn
Contact (Clip)		0,25µm Au	0,76µm Au	2,54µm Sn/Pb	0,25µm Au	0,76µm Au

